

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/19/11504	
1.3 Title of PCI	ST Shenzhen (China) additional source of Carrier Tape and Cover Tape for TSSOP 20 package products	
1.4 Product Category	All products in TSSOP20L from ST Shenzhen	
1.5 Issue date	2019-06-07	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Consumables)	Packing: new supplier for customer deliveries	SH1T---ST SHENZHEN -CHINA

4. Description of change

	Old	New
4.1 Description	single source 3M carrier tape and 3M cover tape	first source 3M carrier Tape and 3M cover tape Second source CPAK carrier tape and CPAK cover tape
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: no change on the product, visual aspect change of the Carrier Tape and Cover Tape. - Fit: no change	

5. Reason / motivation for change

5.1 Motivation	To multiply the source to reduce line down risks.
5.2 Customer Benefit	LOGISTICS IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Not Applicable
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7. Timing / schedule

7.1 Date of qualification results	2019-05-29
7.2 Intended start of delivery	2019-05-29
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11504 Public product.pdf
11504 PCi11504_Additional information.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM8S003F3P6TR	

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